ABSTRACT

ROOM TEMPERATURE WAFER-TO-WAFER BONDING BY POLYDIMETHYLSILOXANE

A method for forming bonds between similar and dissimilar material surfaces, particularly the surfaces of silicon wafers having various devices disposed thereon, wherein such bonds can be formed at room temperature and do not require the application of high pressures or voltages. The bonding material is polydimethylsiloxane, which is transparent and bio-compatible.

(FIGURE 1 IS SUGGESTED FOR PUBLICATION)